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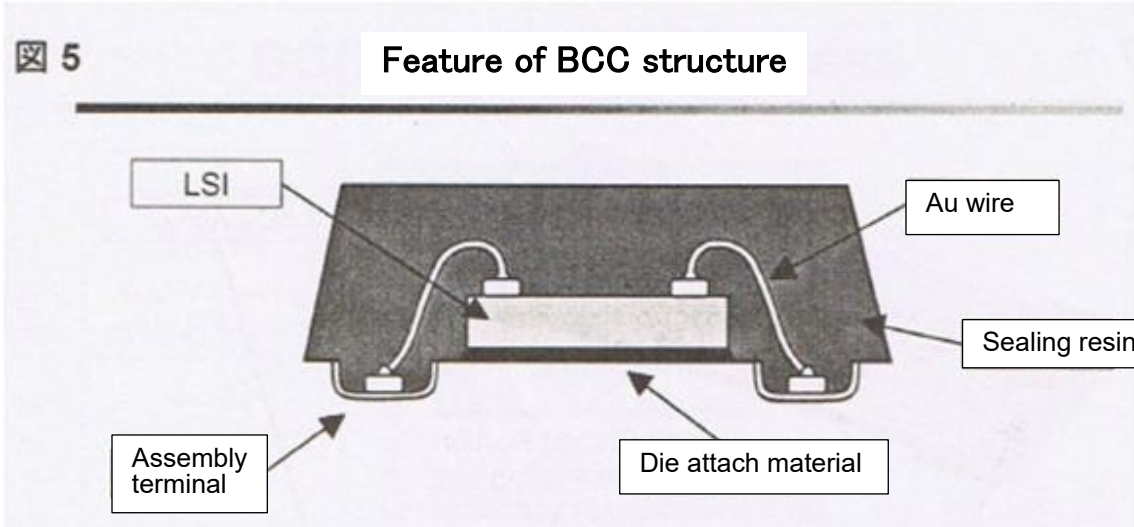
1997

Mass production of BCCs starts

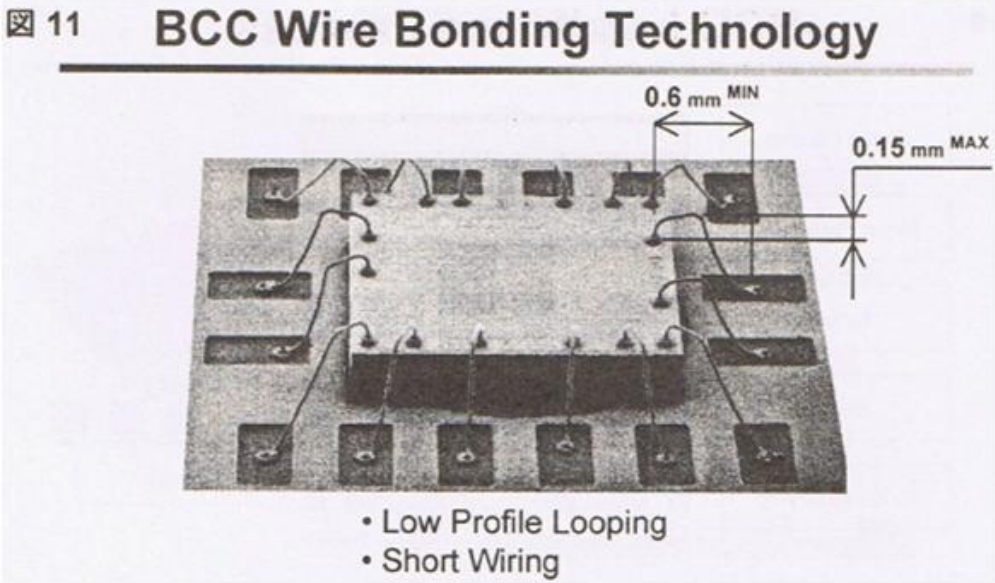
~ Packaging ~

BCC (Bump Chip Carrier) is a package developed by Fujitsu, and the 16-pin type was mass-produced since January 1997. In the manufacturing method, concave part is provided in the lead frame, Au→Pd→Ni→Pd are plated successively, die bonding and wire bonding are performed on elements such as IC, and after transfer molding, the lead frame is removed by etching and CSP (Chip Scale Package) is completed. The figures below show the cross sectional view of BCC structure and the SEM photograph after wire bonding .

Because BCC is small in size, self-inductance and capacitance are smaller compared to SSOP by 25% and 80% respectively. Therefore, it is suitable for communication devices, and then applied to devices such as mobile phones.



- (1) Assembly terminals in resin bump structure (resin protrusion + metal film)
- (2) Interposer-less structure
- (3) Technology for inter-connection between device and terminals.



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